

Fast Switching Emitter Controlled Diode



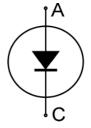


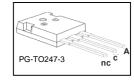




Features:

- 600V Emitter Controlled technology
- Fast recovery
- Soft switching
- Low reverse recovery charge
- Low forward voltage
- 175°C junction operating temperature
- Easy paralleling
- Pb-free lead plating; RoHS compliant
- Complete product spectrum and PSpice Models: http://www.infineon.com





Applications:

- Welding
- Motor drives

Туре	V_{RRM}	I _F	V _{F,Tj=25°C}	$T_{\rm j,max}$	Marking	Package
IDW100E60	600V	100A	1.65V	175°C	D100E60	PG-TO247-3

Maximum Ratings

Parameter	Symbol	Value	Unit
Repetitive peak reverse voltage	V_{RRM}	600	V
Continuous forward current			
$T_{\rm C}$ = 25°C	,	150	
$T_{\rm C} = 90^{\circ}{\rm C}$	I _F	104	A
$T_{\rm C}$ = 100°C		96	
Surge non repetitive forward current	,	400	_
$T_{\rm C}$ = 25°C, $t_{\rm p}$ = 10 ms, sine halfwave	I _{FSM}	400	A
Maximum repetitive forward current	,	200	_
$T_{\rm C}$ = 25°C, $t_{\rm p}$ limited by $t_{\rm j,max}$, D = 0.5	I _{FRM}	300	A
Power dissipation			
$T_{\rm C} = 25^{\circ}{\rm C}$	D	375	14/
$T_{\rm C} = 90^{\circ}{\rm C}$	P_{tot}	212	W
$T_{\rm C} = 100^{\circ}{\rm C}$		198	
Operating junction temperature	T _j	-40+175	
Storage temperature	$T_{ m stg}$	-55+150	□°C
Soldering temperature 1.6mm (0.063 in.) from case for 10 s	Ts	260	





Thermal Resistance

Parameter	Symbol	Conditions	Max. Value	Unit
Characteristic				I
Thermal resistance,	R_{thJC}		0.40	K/W
junction – case				
Thermal resistance,	R_{thJA}		40	
junction – ambient				

Electrical Characteristic, at $T_j = 25$ °C, unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
raiametei	Syllibol	Conditions	min.	typ.	max.	Onne
Static Characteristic						
Collector-emitter breakdown voltage	V_{RRM}	$I_R=0.25$ mA	600	-	-	V
Diode forward voltage	V_{F}	I _F =100A				
		<i>T</i> _j =25°C	-	1.65	2.0	
		<i>T</i> _j =175°C	-	1.65	-	
Reverse leakage current	I_{R}	V _R =600V				μΑ
		<i>T</i> _j =25°C	-	-	40	
		<i>T</i> _j =175°C	-	-	3300	
Dynamic Electrical Characteristics						
Diode reverse recovery time	t_{rr}	<i>T</i> _j =25°C	-	120	-	ns

Dynamic Electrical Characteristics						
Diode reverse recovery time	trr	<i>T</i> _j =25°C	-	120	-	ns
Diode reverse recovery charge	Q _{rr}	$V_R=400V$,	-	3.6	-	μC
Diode peak reverse recovery current	I _{rr}	$I_{\rm F} = 100 \rm A$	-	49.5	-	Α
Diode peak rate of fall of reverse recovery current during $t_{\rm b}$	dI _{rr} /dt	dI_{F}/dt =1200A/ μ s	-	750	-	A/µs
Diode reverse recovery time	trr	<i>T</i> _j =125°C	-	168	-	ns
Diode reverse recovery charge	Q _{rrm}	$V_R=400V$,	-	5.8	-	μC
Diode peak reverse recovery current	I _{rr}	$I_{\rm F} = 100 \rm A$	-	61.6	-	Α
Diode peak rate of fall of reverse recovery current during $t_{\rm b}$	dI _{rr} /dt	dI_{F}/dt =1200A/ μ s	-	705	-	A/µs
						•
Diode reverse recovery time	trr	<i>T</i> _j =175°C	-	200	-	ns
Diode reverse recovery charge	Q _{rrm}	$V_R=400V$,	-	7.8	-	μC
Diode peak reverse recovery current	I _{rr}	$I_{\rm F} = 100 \rm A$	-	67.0	-	Α
Diode peak rate of fall of reverse recovery current during $t_{\rm b}$	dI _{rr} /dt	$dI_{\rm F}/dt$ =1200A/ μ s	-	650	-	A/µs



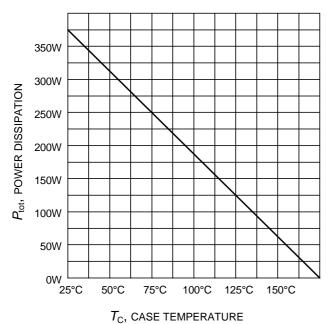


Figure 1. Power dissipation as a function of case temperature $(T_i \le 175^{\circ}\text{C})$

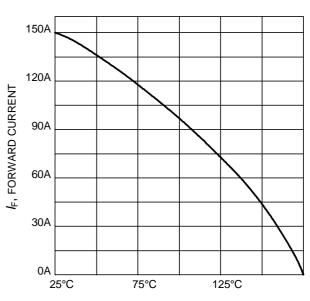


Figure 2. Diode forward current as a function of case temperature $(T_i \le 175^{\circ}C)$

 $T_{\rm C}$, CASE TEMPERATURE

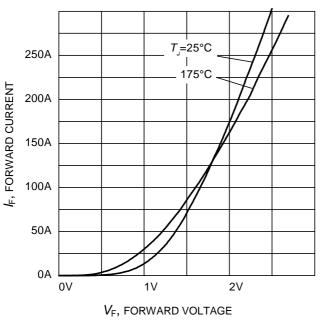


Figure 3. Typical diode forward current as a function of forward voltage

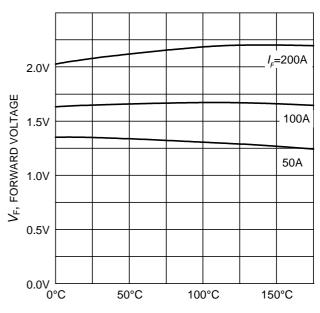


Figure 4. Typical diode forward voltage as a function of junction temperature

 $T_{\rm J}$, JUNCTION TEMPERATURE



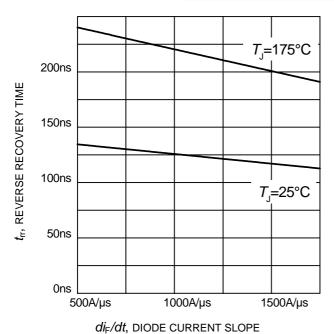
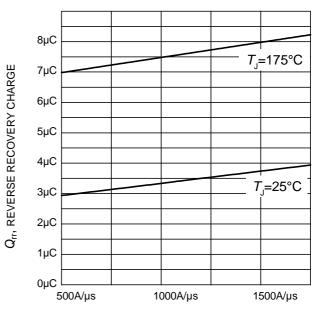


Figure 5. Typical reverse recovery time as a function of diode current slope $(V_R=400V, I_F=100A, Dynamic test circuit in Figure E)$



di_F/dt, DIODE CURRENT SLOPE

Figure 6. Typical reverse recovery charge as a function of diode current slope $(V_R = 400\text{V}, I_F = 100\text{A}, \text{Dynamic test circuit in Figure E})$

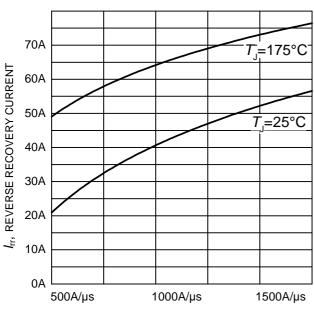
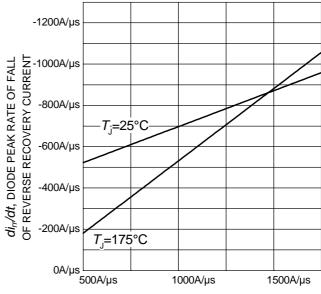


Figure 7. Typical reverse recovery current as a function of diode current slope

di_F/dt, DIODE CURRENT SLOPE

($V_R = 400V$, $I_F = 100A$, Dynamic test circuit in Figure E)



 $di_{\rm F}/dt$, DIODE CURRENT SLOPE

Figure 8. Typical diode peak rate of fall of reverse recovery current as a function of diode current slope (V_R =400V, I_F =100A, Dynamic test circuit in Figure E)



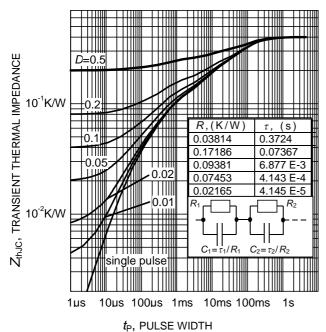
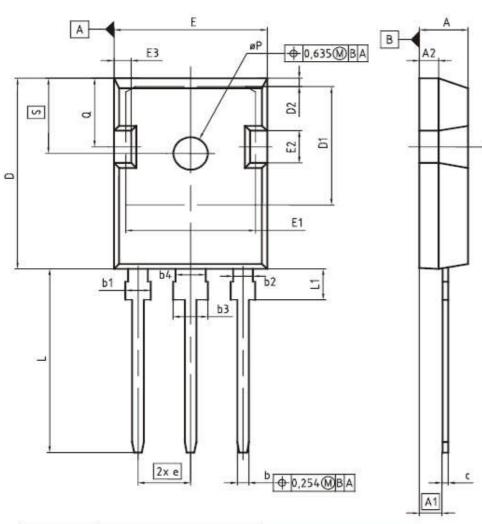


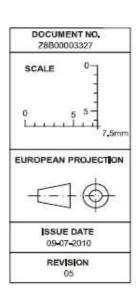
Figure 9. Diode transient thermal impedance as a function of pulse width $(D=t_{\rm P}/T)$



PG-TO247-3



DBM	MILLIM	ETERS	NCHES		
DEM	MIN	MAX	MIN	MAX	
A	4,83	5,21	0.190	0,205	
A1	2,27	2,54	0.089	0,100	
A2	1.85	2,16	0.073	0.085	
b	1.07	1,33	0,042	0,052	
b1	1.90	2.41	0.075	0,095	
b2	1.90	2.16	0,075	0,085	
b3	2,87	3.38	0.113	0.133	
b4	2,87	3.13	0,113	0,123	
c	0,55	0.68	0,022	0,027	
D	20,80	21,10	0,819	0.831	
D1	16,25	17.65	0,640	0,695	
D2	0.95	1.35	0.037	0,053	
E	15.70	16.13	0.618	0,635	
E1	13.10	14.15	0,516	0,557	
E2	3,68	5.10	0.145	0,201	
E3	1.00	2.60	0,039	0.102	
e	5.	44 (BSC)	0.2	214 (BSC)	
N		3		3	
L	19,80	20,32	0.780	0,800	
L1	4.10	4.47	0.161	0,176	
øΡ	3,50	3,70	0.138	0,146	
Q	5.49	6.00	0.216	0.236	
S	6,04	6,30	0,238	0,248	





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